

Memory Product Specification

DDR3-1333 SO-DIMM

Description

The Module is DDR3-1333 CL9 Small Outline Memory module. The Module density from 1GB to 4GB, it consists 128M/256Mx8 bit DDR3-1333MHz Synchronous DRAMs in FBGA packages, Memory Module intended for mounting into 204-pin edge connector sockets. The electrical and mechanical specifications are as follows.

Features

- JEDEC Standard
- DDR3 Speed Grade : 1333Mbps
- SO-DIMM : 204-pin
- Memory Organization : x8 FBGA DRAM chip
- DDR3 DRAM interface : SSTL_15
- CAS latency : 9-9-9
- Bandwidth : 10600MB/s
- VDD voltage : 1.5+-0.075V
- VDDQ voltage : 1.5+-0.075V
- Serial presence detect with EEPROM.
- PCB height : **1.181 inch**
- RoHS Compliant
- Application : NoteBook